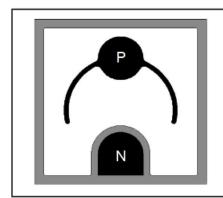


## ELC-525-34

Radiation	Type	Electrodes	
green	GaN / sapphire	N+P-up	



P-electrode N-electrode Sapphire-substrate

Chip size: 15 mil x 15 mil (380 ± 25  $\mu$ m x 380 ± 25  $\mu$ m)
Thickness: 3.5 mil (90 ± 10  $\mu$ m)
N, P bonding pads: 4 mil (100 ± 10  $\mu$ m), Au alloy

## **Absolute Maximum Ratings**

T<sub>amb</sub>= 25°C, unless otherwise specified

Parameter	Symbol	Rating	Unit
Forward current	l <sub>F</sub>	30	mA

## **Optical and Electrical Characteristics**

T<sub>amb</sub>= 25°C, unless otherwise specified

Parameter	Symbol	Cond.	Min	Тур	Max	Unit
Forward voltage	V <sub>F</sub>	I <sub>F</sub> =20 mA	2.8	3.0	3.8	V
Reverse current	I <sub>R</sub>	V <sub>R</sub> =5 V			2	μΑ
Luminous intensity*	I <sub>V</sub>	I <sub>F</sub> =20 mA		850	1200	mcd
Radiant power**	Фе	I <sub>F</sub> =20 mA		9		mW
TK of radiant power	TKΦ <sub>e</sub>	I <sub>F</sub> =20 mA		-0.12		%/K
Dominant wavelength	λ <sub>D</sub>	I <sub>F</sub> =20 mA	515	525	535	nm
FWHM	Δλ <sub>0.5</sub>	I <sub>F</sub> =20 mA		35		nm

<sup>\*</sup>Measured on gold plate; \*\*measured on TO-header with epoxy encapsulation

## **Packing**

Dice on adhesive film with wire-bond on top

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The above specifications are for reference purpose only and subjected to change without prior notice



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